

### **Featured**

- 1204 0.8mm SMD LED
- High Brightness
- AllnGaP / InGaN Technology
- High Reliability
- Clear Lens

## **Applications**

- Consumer Electronics
- Wearables
- Automobile After Market
- Industrial Equipment

## **Description**

The IN-S124TCRRGB is a 1204 package RGB LED with reverse mount and versatile design capabilities. It is a PCB type molding style LED which can be used in various applications.

### **Recommended Solder Pattern**

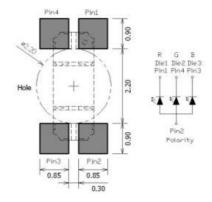


Figure 1. IN-S124TCR Solder Pattern

# Package Dimensions in mm

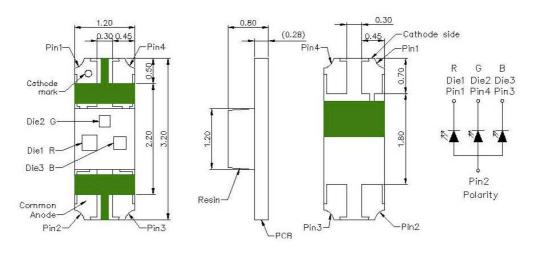


Figure 2. IN-S124TCR Package Dimensions



# Absolute Maximum Rating at 25°C (Note 1)

Product	Emission Color	P <sub>d</sub> (mW)	I <sub>F</sub> (mA)	I <sub>FP</sub> * (mA)	V <sub>R</sub> (V)	T <sub>OP</sub> (°C)	T <sub>ST</sub> (°C)
	Red	48	20	40	5	-40°C~+85°C	-40°C~+100°C
IN-S124TCRRGB	Green	78	20	40	5	-40°C~+85°C	-40°C~+100°C
	Blue	78	20	60	5	-40°C~+85°C	-40°C~+100°C

#### **Notes**

1. Condition for IFP is pulse of 1/10 duty and 0.1msec width

#### **ESD Precaution**

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

# **Electrical Characteristics** $T_A = 25\%$ (Note 1)

	Emission	V <sub>F</sub> (V)			λ(nm)	Viewing Angle	I* <sub>v</sub> (mcd)		
Product	Color	I <sub>F</sub> (mA)	typ.	max	$\lambda_{D}$	$\lambda_{ extsf{P}}$	Δλ	2 0 1/2	typ.
IN-S124TCRRGB	Red	20	2.0	2.4	624	632	20	X = 140 Y = 125	71.5
	Green	20	3.3	3.9	525	520	30	X = 140 Y = 125	285.0
	Blue	20	3.3	3.9	470	468	40	X = 140 Y = 125	71.5

#### **Notes**

<sup>1.</sup> Performance guaranteed only under conditions listed in above tables.

**Luminous Intensity (Iv) Bin:** 

Color	Bin Code	Spec. Range
	N	28.5-45.0 mcd
Do J	Р	45.0-71.5 mcd
Red	Q	71.5-112.5 mcd
	R	112.5-180.0 mcd
	R	112.5-180.0 mcd
_	S	180.0-285.0 mcd
Green	Т	285.0-360.0 mcd
	U	360.0-450.0 mcd
	N	28.5-45.0 mcd
Blue	Р	45.0-71.5 mcd
	Q	71.5-112.5 mcd
	R	112.5-180.0 mcd

Note: It maintains a tolerance of ±10% on luminous intensity

### **Color Bin:**

Color	Bin Code	Spec. Range		
Red	AD	615.0-630.0 nm		
	Α	515.0- 520.0 nm		
Green	В	520.0- 525.0 nm		
Green	С	525.0- 530.0 nm		
	D	530.0- 535.0 nm		
	E	535.0-540.0 nm		
	AA	460.0-465.0nm		
Blue	AB	465.0-470.0 nm		
Diue	AC	470.0-475.0 nm		
	AD	475.0-480.0 nm		

Note: It maintains a tolerance of ±0.5nm on color

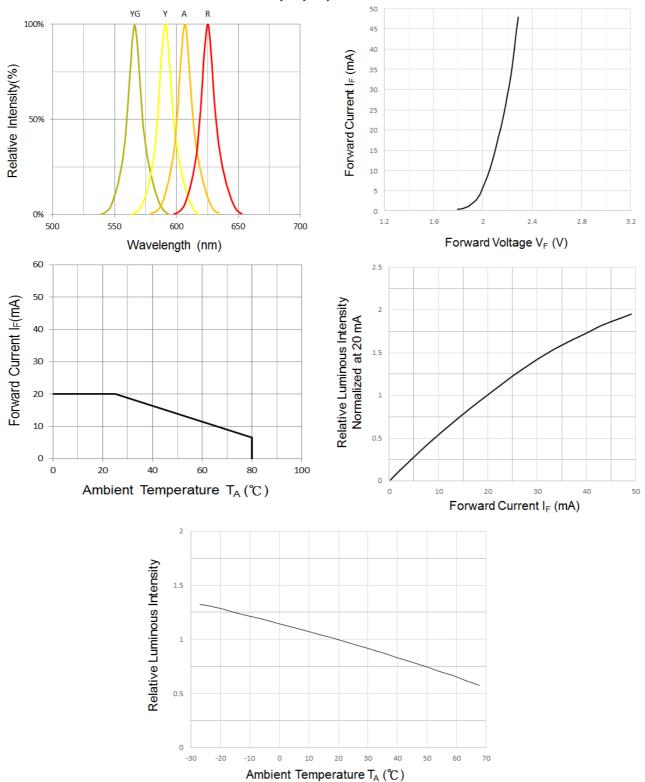


Forward Voltage (Vf) Bin:

Color	Bin Code	Spec. Range
Red	E18	1.6~2.4 V
	G8	2.7-2.9 V
	H7	2.9-3.1 V
Cuan	Н8	3.1-3.3 V
Green	J7	3.3-3.5 V
	J8	3.5-3.7 V
	K7	3.7-3.9 V
	G8	2.7-2.9 V
	H7	2.9-3.1 V
Blue	Н8	3.1-3.3 V
Diue	J7	3.3-3.5 V
	J8	3.5-3.7 V
	K7	3.7-3.9 V

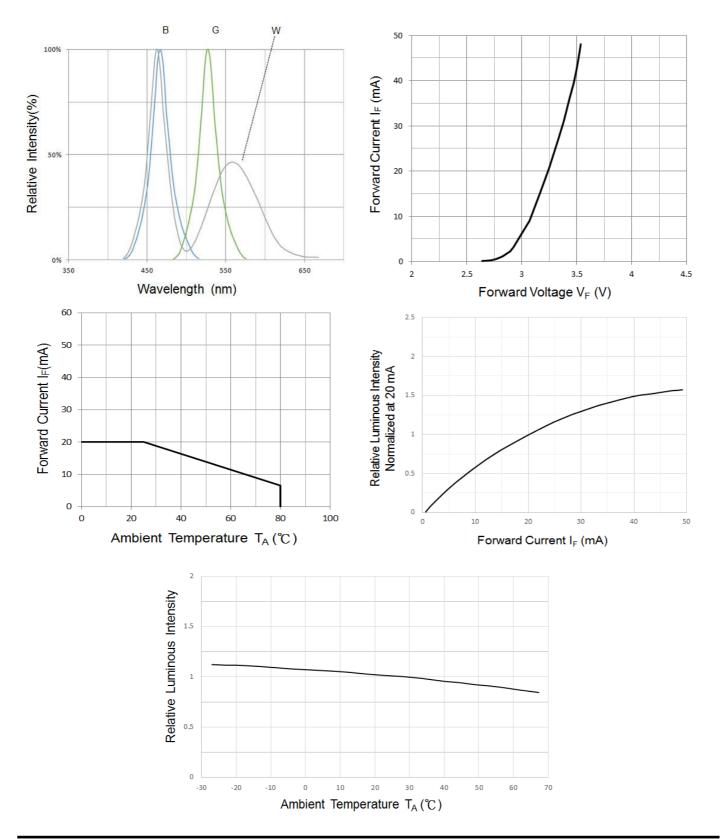
Note: It maintains a tolerance of ±0.05V on forward voltage measurements

# Typical Characteristic Curves - YG, Y, A, R



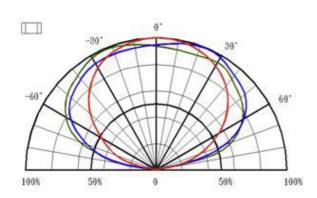


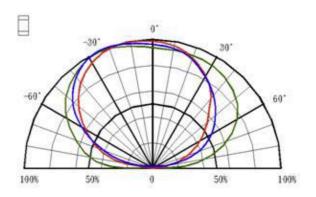
# Typical Characteristic Curves - B, G, W





# **Typical Characteristic Curves – Radiation Pattern**

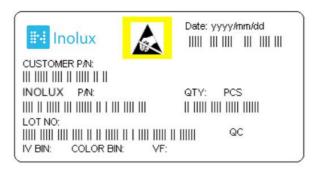




# **Ordering Information**

Product	Emission Color	Technology	Test Current I <sub>F</sub> (mA)	Luminous Intensity Iv (mcd) (Typ.)	Forward Voltage V <sub>F</sub> (V) (Typ.)	Orderable Part Number
	Red	AllnGaP	20	71.5	2.0	
IN-S124TCRRGB	Green	InGaN	20	285.0	3.3	IN-S124TCRRGB
	Blue	InGaN	20	71.5	3.3	

## **Label Specifications**



## Inolux P/N:

I	N	-	S	1	2	4	Т	С	R			R	G	В	-	Х	Χ	х х
			Material	Pa	ackag	e	Varia	ation	Orientation	Current	Lens		Color	•			iston tamp	nized o-off
	olux MD		S = PCB Type	1			2 x 1.2 ri-chip		R = Reverse Mount	(Blank) = 20mA	(Blank) = Clear U = Diffused	G:	=624n =525n =470n	ım				

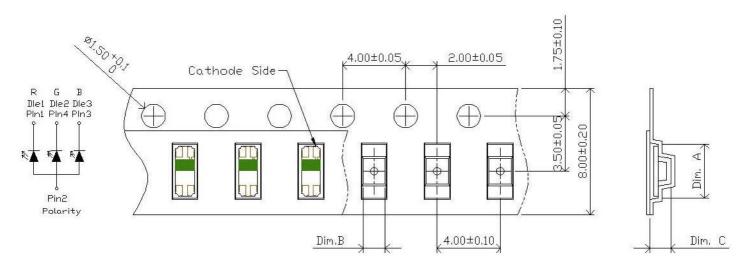
#### Lot No.:

Z	2	0	1	7	01	24	001
Internal		Voor (2017	2019 \	Month	Data	Sorial	
Tracker		real (2017	, 2018,)		IVIOIILII	Date	Serial



# Packaging Information: 2000pcs Per Reel

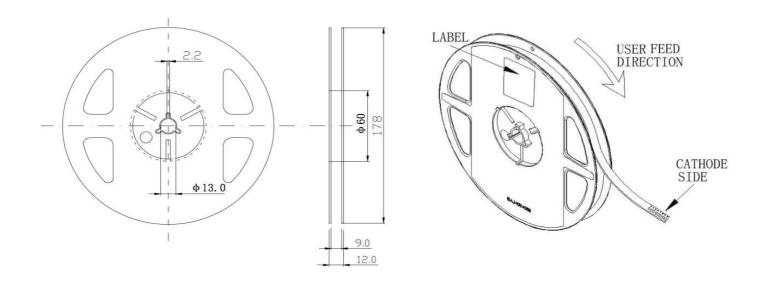
# Tape Dimension



Part No.	Dim. A	Dim. B	Dim. C	Q'ty/Reel
IN-S124TCRRGB	3.4±0.10	1.42±0.10	1.37±0.10	3K

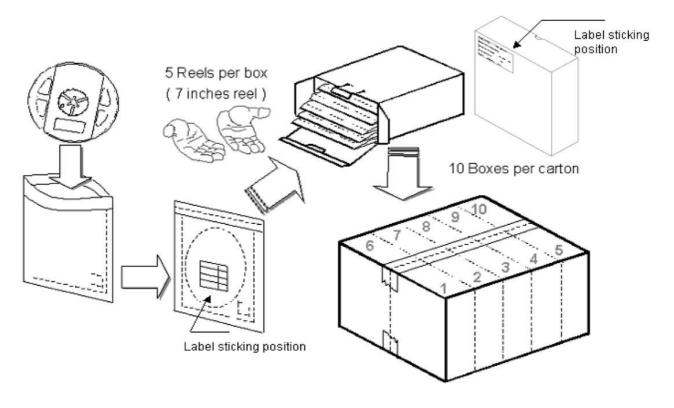
Unit: mm

## **Reel Dimension**





# **Packing Dimension**



5 boxes per carton are available depending on shipment quantity.

Specification	Material	Quantity
Per EIA 481-1A specs	Conductive black tape	3000pcs per reel
Per EIA 481-1A specs	Conductive black	
IN standard	Paper	
220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
IN standard	Paper	Non-specified
	Per EIA 481-1A specs Per EIA 481-1A specs IN standard 220x240mm	Per EIA 481-1A specs Conductive black tape Per EIA 481-1A specs Conductive black IN standard Paper 220x240mm Aluminum laminated bag/ no-zipper

#### Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv,  $\lambda_D$  and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

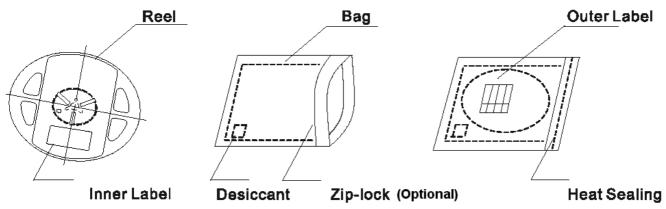


## **Dry Pack**

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

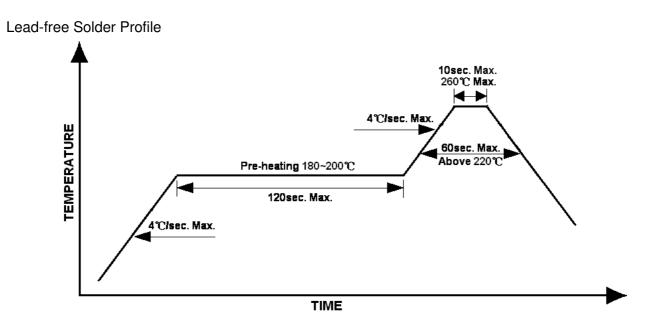
Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



## **Reflow Soldering**

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):





### **Precautions**

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AllnGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

## Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

## Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

### **Cautions of Pick and Place**

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.



# Reliability

To JEDEC Level 2	liability			
Section   Sect	Item			Conditions
Precondition	item			
To JEDEC Level 2			J-STD-020	
Solderability	Precondition			
And CNS-5068		to JEDEC Level 2		168hrs
Tinning: À: 215°C/ 3+1s or B: 260°C/ 10+1s  CNS-5067  Dipping soldering terminal only Soldering bath temperature A: 2604/-5°C; 10+/-1s B: 350+/-10°C; 3+/-0.5s  1Q/ 1/ 40/ 0  CNS-11829  1) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs  High humidity, high temperature bias  High temperature bias  1Q/ 1/ 40/ 0  Pulse life test  1Q/ 1/ 40/ 0  Temperature cycle  1Q/ 1/ 76/ 0  JESD-A104-A IEC 68-2-14, Nb  IEC 68-2-14, Nb  Tinning: À: 215°C/ 3+1s or B: 260°C/ 10+1s Dipping soldering terminal only Soldering bath temperature A: 2604/-5°C; 10+/-10s B: 350+/-10°C; 3+/-0.5s  1) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs  Tamb: 85°C Humidity: 85% R.H., IF=5mA Duration: 1000hrs  Tamb: 55°C IF=20mA Duration: 1000hrs  Tamb25°C, If=20mA, Ip=100mA, Duty cycle=0.125 (tp=125 \( \psi\$ s,T=1sec) Duration 500hrs)  A cycle: -40 degree C 15min; +85 degree C 15min Thermal steady within 5 min 300 cycles 2 chamber/ Air-to-air type  High humidity storage test High temperature storage test Low temperature 1Q/ 1/ 40/ 0  CNS-6118  -40+5°C for 500hrs		1Q/ 1/ 22/ 0	JESD22-B102-B	Accelerated aging 155°C/ 24hrs
CNS-5067   Dipping soldering terminal only Soldering bath temperature A: 260+/-5°C; 10+/-1s B: 350+/-10°C; 34/-0.5s     Operating life test	Solderability		And CNS-5068	Tinning speed: 2.5+0.5cm/s
Soldering bath temperature   Soldering bath temperature   A: 260+/-5°C; 10+/-1s	_			Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s
A: 260+/-5°C; 10+/-1s     B: 350+/-10°C; 3+/-0.5s     CNS-11829   1.) Precondition: 85°C baking for 24hrs     S5°C / 60%R.H. for 168hrs     2.) Tamb25°C; IF=20mA; duration 1000hrs     High humidity, high temperature bias     High temperature bias     1Q/ 1/ 40/ 0   IN specs.     Tamb: 55°C     Humidity: 85% R.H., IF=5mA     Duration: 1000hrs     Tamb: 55°C     Humidity: 85% R.H., IF=5mA     Duration: 1000hrs     Tamb: 55°C     High temperature bias     1Q/ 1/ 40/ 0   IN specs.     Tamb: 55°C     IF=20mA, IP=100mA, Duty     Cycle=0.125 (tp=125 \( \mu\) s,T=1sec)     Duration: 500hrs     Temperature cycle			CNS-5067	Dipping soldering terminal only
B: 350+/-10°C; 3+/-0.5s     1Q/ 1/ 40/ 0   CNS-11829   1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs     High humidity, high temperature bias   1Q/ 1/ 45/ 0   JESD-A101-B   Tamb: 85°C     High temperature bias   1Q/ 1/ 20   IN specs.   Tamb: 55°C     IF=20mA   Duration: 1000hrs     Tamb: 55°C   IF=20mA, IP=100mA, Duty cycle=0.125 (IF=20mA,, IP=100m	Resistance to			Soldering bath temperature
B: 350+/-10°C; 3+/-0.5s     1Q/ 1/ 40/ 0   CNS-11829   1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs     High humidity, high temperature bias   1Q/ 1/ 45/ 0   JESD-A101-B   Tamb: 85°C     High temperature bias   1Q/ 1/ 20   IN specs.   Tamb: 55°C     IF=20mA   Duration: 1000hrs     Tamb: 55°C   IF=20mA, IP=100mA, Duty cycle=0.125 (IF=20mA,, IP=100m	soldering heat			A: 260+/-5°C; 10+/-1s
Operating life test         85°C/ 60%R.H. for 168hrs           High humidity, high temperature bias         1Q/ 1/ 45/ 0           High temperature bias         1Q/ 1/ 20           High temperature bias         IN specs.           Tamb: 55°C Humidity: 85% R.H., IF=5mA Duration: 1000hrs           High temperature bias         1Q/ 1/ 20           High temperature bias         IN specs.           Tamb: 55°C IF=20mA Duration: 1000hrs           Tamb25°C, If=20mA, Ip=100mA, Duty cycle=0.125 (tp=125 μ s,T=1sec) Duration 500hrs)           Temperature cycle         1Q/ 1/ 76/ 0           JESD-A104-A IEC 68-2-14, Nb         A cycle: -40 degree C 15min; +85 degree C 15min Thermal steady within 5 min 300 cycles 2 chamber/ Air-to-air type           High humidity storage test         1Q/ 1/ 40/ 0           High temperature storage test         1Q/ 1/ 40/ 0           Low temperature storage test         1Q/ 1/ 40/ 0           Low temperature         1Q/ 1/ 40/ 0           CNS-6118         -40+5°C for 500hrs				B: 350+/-10°C; 3+/-0.5s
2.) Tamb25°C; IF=20mA; duration 1000hrs		1Q/ 1/ 40/ 0	CNS-11829	1.) Precondition: 85°C baking for 24hrs
High humidity, high temperature bias         1Q/ 1/ 45/ 0         JESD-A101-B         Tamb: 85°C Humidity: 85% R.H., IF=5mA Duration: 1000hrs           High temperature bias         1Q/ 1/ 20         IN specs.         Tamb: 55°C IF=20mA Duration: 1000hrs           Pulse life test         1Q/ 1/ 40/ 0         Tamb: 55°C IF=20mA, Ip=100mA, Duty cycle=0.125 (tp=125 μ s,T=1sec) Duration 500hrs)           Pulse life test         1Q/ 1/ 76/ 0         JESD-A104-A IEC 68-2-14, Nb         A cycle: -40 degree C 15min; +85 degree C 15min; +85 degree C 15min Thermal steady within 5 min. 300 cycles 2 chamber/ Air-to-air type           High humidity storage test         1Q/ 1/ 40/ 0         CNS-6117         60+3°C 90+5/-10% R.H. for 500hrs           High temperature storage test         1Q/ 1/ 40/ 0         CNS-554         100+10°C for 500hrs           Low temperature         1Q/ 1/ 40/ 0         CNS-6118         -40+5°C for 500hrs	Operating life test			85°C/ 60%R.H. for 168hrs
Humidity: 85% R.H., IF=5mA				2.) Tamb25°C; IF=20mA; duration 1000hrs
Humidity: 85% R.H., IF=5mA	High humidity,	1Q/ 1/ 45/ 0	JESD-A101-B	Tamb: 85°C
Duration: 1000hrs	high temperature			Humidity: 85% R.H., IF=5mA
IF=20mA     Duration: 1000hrs     Tamb25°C, If=20mA, Ip=100mA, Duty     cycle=0.125 (tp=125 μ s,T=1sec)     Duration 500hrs     Temperature     Cycle	bias			Duration: 1000hrs
Duration: 1000hrs   Duration: 1000hrs   Tamb25°C, If=20mA,, Ip=100mA, Duty   Cycle=0.125 (tp=125 μ s,T=1sec)   Duration 500hrs   EC 68-2-14, Nb   Thermal steady within 5 min   300 cycles   2 chamber/ Air-to-air type   Air-to-air type   Storage test   Duration 500hrs   Duratio	Lligh tomporature	1Q/ 1/ 20	IN specs.	Tamb: 55°C
Duration: 1000nrs				IF=20mA
Pulse life test	bias			Duration: 1000hrs
Duration 500hrs   Duration 500hrs		1Q/ 1/ 40/ 0		Tamb25°C, If=20mA,, Ip=100mA, Duty
Temperature cycle  Temperature c	Pulse life test			cycle=0.125 (tp=125 $\mu$ s,T=1sec)
IEC 68-2-14, Nb				Duration 500hrs)
Temperature cycle		1Q/ 1/ 76/ 0	JESD-A104-A	A cycle: -40 degree C 15min; +85 degree C
Thermal steady within 5 min   300 cycles   2 chamber/ Air-to-air type	T		IEC 68-2-14, Nb	
300 cycles   2 chamber/ Air-to-air type			,	Thermal steady within 5 min
High humidity storage test       1Q/ 1/ 40/ 0       CNS-6117       60+3°C 90+5/-10% R.H. for 500hrs         High temperature storage test       1Q/ 1/ 40/ 0       CNS-554       100+10°C for 500hrs         Low temperature       1Q/ 1/ 40/ 0       CNS-6118       -40+5°C for 500hrs	cycle			
High humidity storage test       1Q/ 1/ 40/ 0       CNS-6117       60+3°C 90+5/-10% R.H. for 500hrs         High temperature storage test       1Q/ 1/ 40/ 0       CNS-554       100+10°C for 500hrs         Low temperature       1Q/ 1/ 40/ 0       CNS-6118       -40+5°C for 500hrs				2 chamber/ Air-to-air type
storage test         90+5/-10% R.H. for 500hrs           High temperature storage test         1Q/ 1/ 40/ 0         CNS-554         100+10°C for 500hrs           Low temperature         1Q/ 1/ 40/ 0         CNS-6118         -40+5°C for 500hrs	High humidity	1Q/ 1/ 40/ 0	CNS-6117	
High temperature         1Q/ 1/ 40/ 0         CNS-554         100+10°C for 500hrs           storage test         Low temperature         1Q/ 1/ 40/ 0         CNS-6118         -40+5°C for 500hrs	storage test			90+5/-10% R.H. for 500hrs
storage test Low temperature 1Q/ 1/ 40/ 0 CNS-6118 -40+5°C for 500hrs	High temperature	1Q/ 1/ 40/ 0	CNS-554	100+10°C for 500hrs
Low temperature   1Q/ 1/ 40/ 0   CNS-6118   -40+5°C for 500hrs	storage test			
	Low temperature	1Q/ 1/ 40/ 0	CNS-6118	-40+5°C for 500hrs
	storage test			



**Revision History** 

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	04-10-2017
Updated	1	1.1	10-25-2022

### **DISCLAIMER**

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- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.